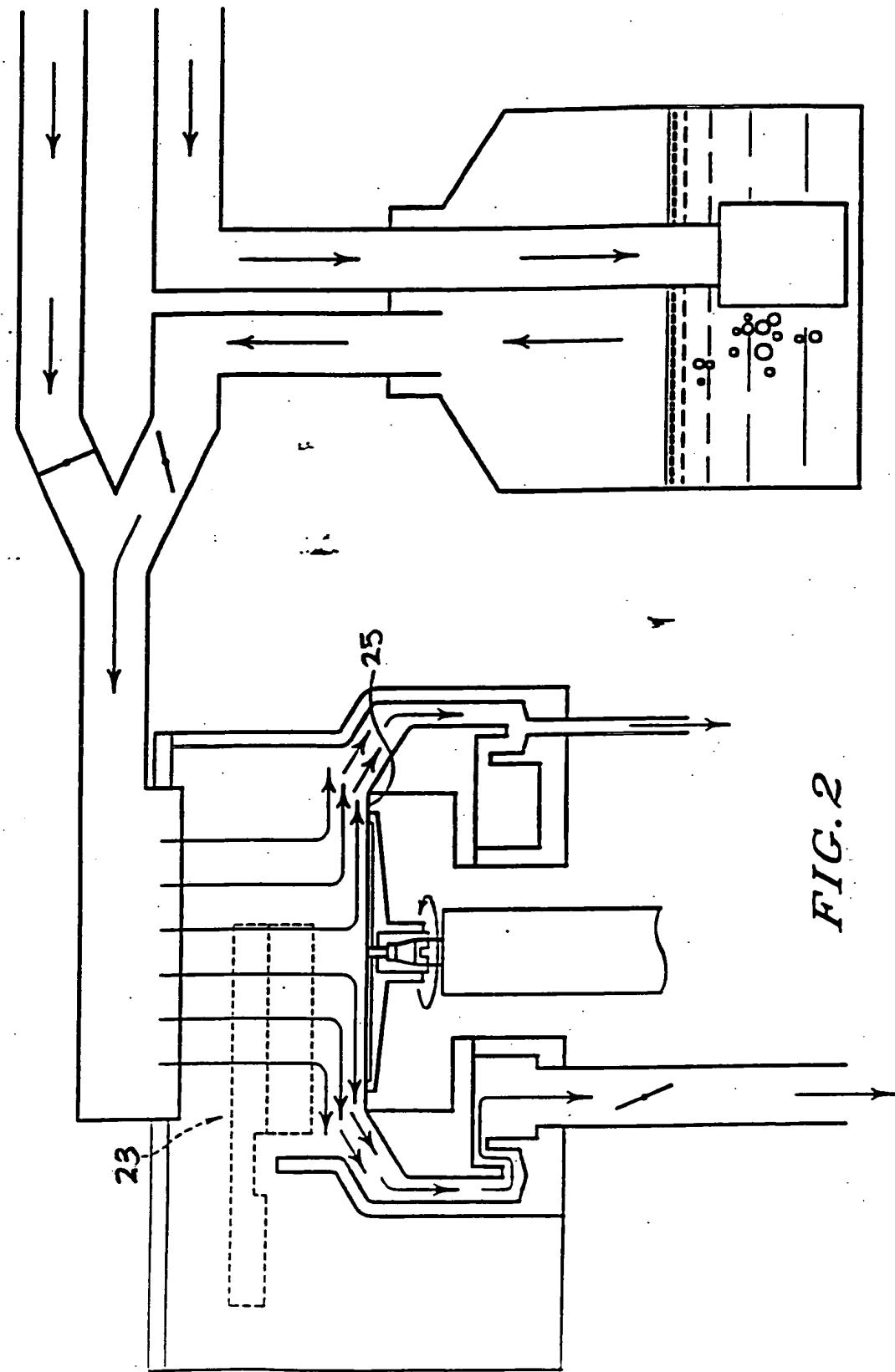


FIG. 1

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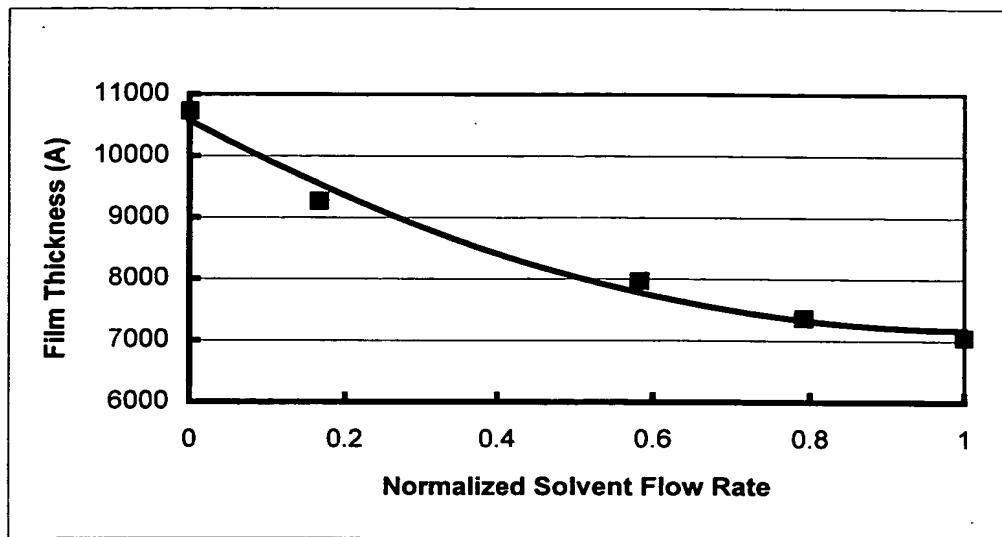


Figure 3a) Mean resist film thickness as a function of solvent concentration at a fixed drying spin speed . Mean film thickness can be varied close to 4000Å by varying the solvent concentration at a fixed 2000 rpm.

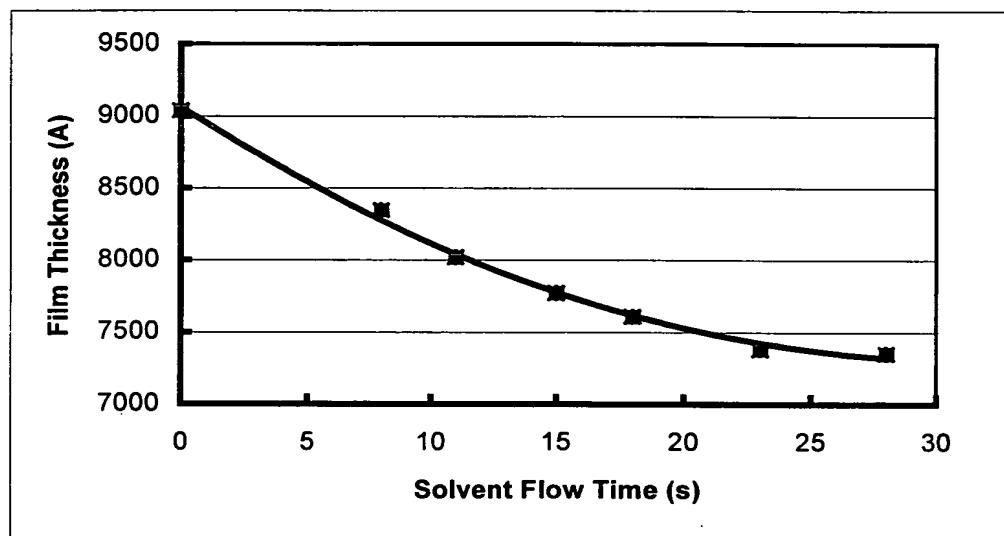


Figure 3b): Film thickness as a function of solvent flow time for a working example.

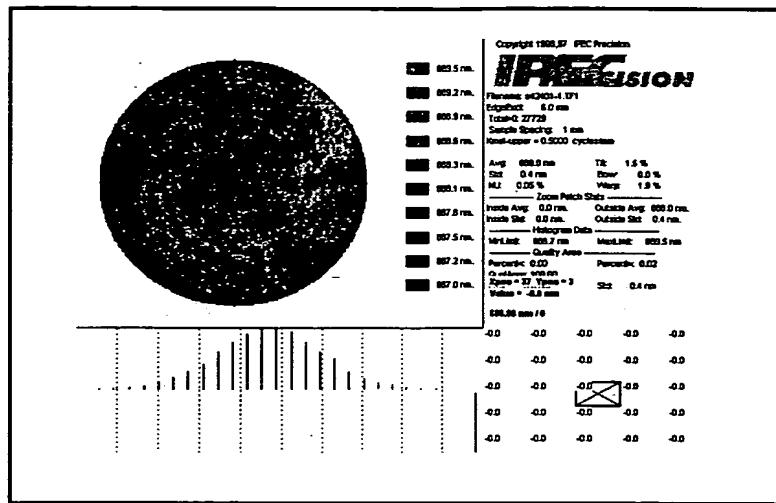
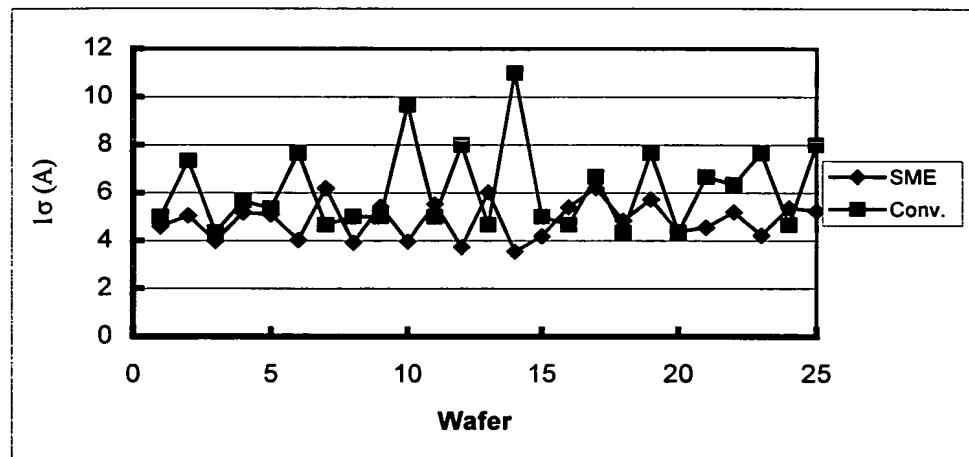


Figure 4: A typical film thickness profile, as measured by 30,000 pts film thickness measurement tool, has a  $1\sigma$  uniformity of 4 Å (0.045%) for 8880 Å target thickness.



	Conventional Coater	Invention
$1\sigma_{ave}$	5.67 Å	4.86 Å
$1\sigma_{band}$	4.5 Å	2.2 Å

Figure 5) Film uniformity comparison between the invention (SME) and conventional spin coaters.

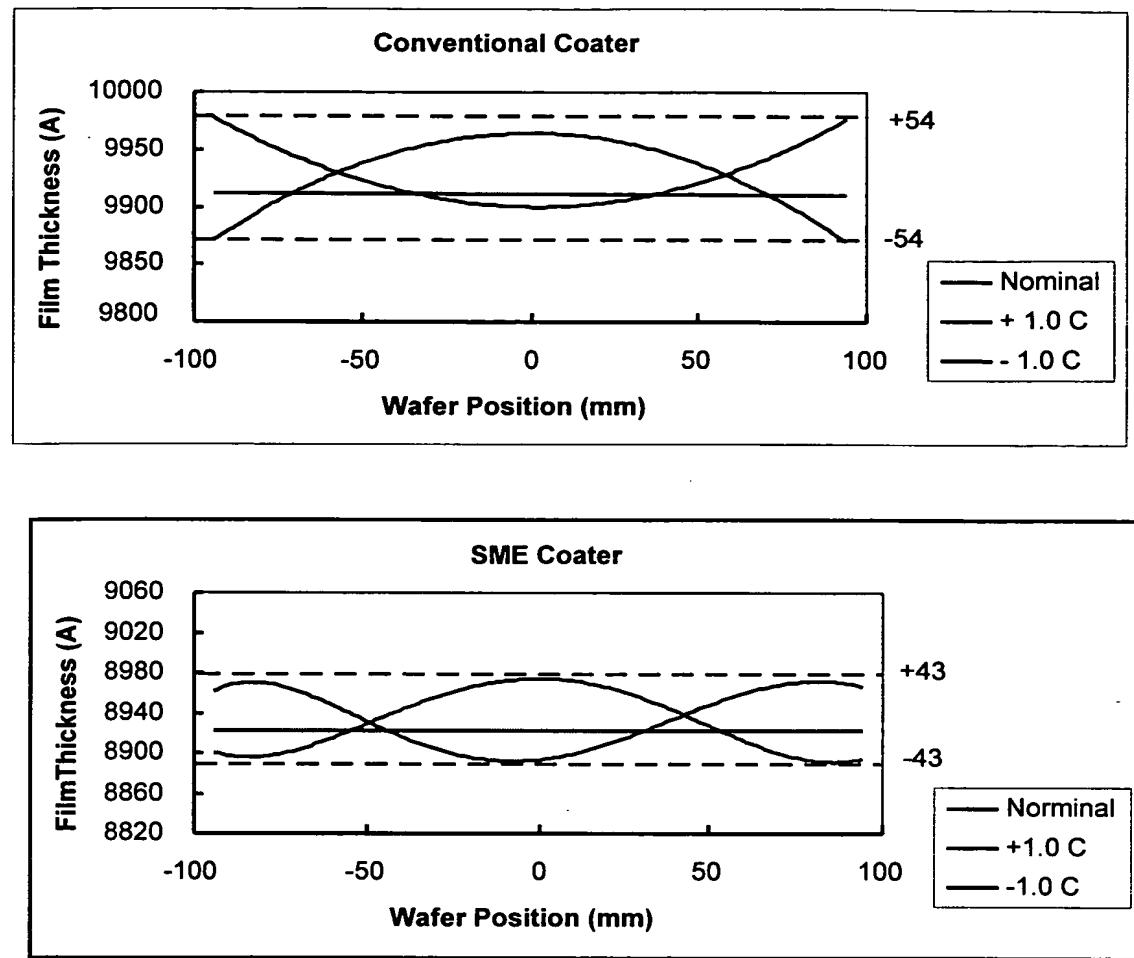


Figure 6: Resist temperature latitude comparison between the invention (SME) and conventional coaters for 200mm wafers. The SME coater resist temperature latitude of film uniformity is 36% wider than that of a conventional coater.

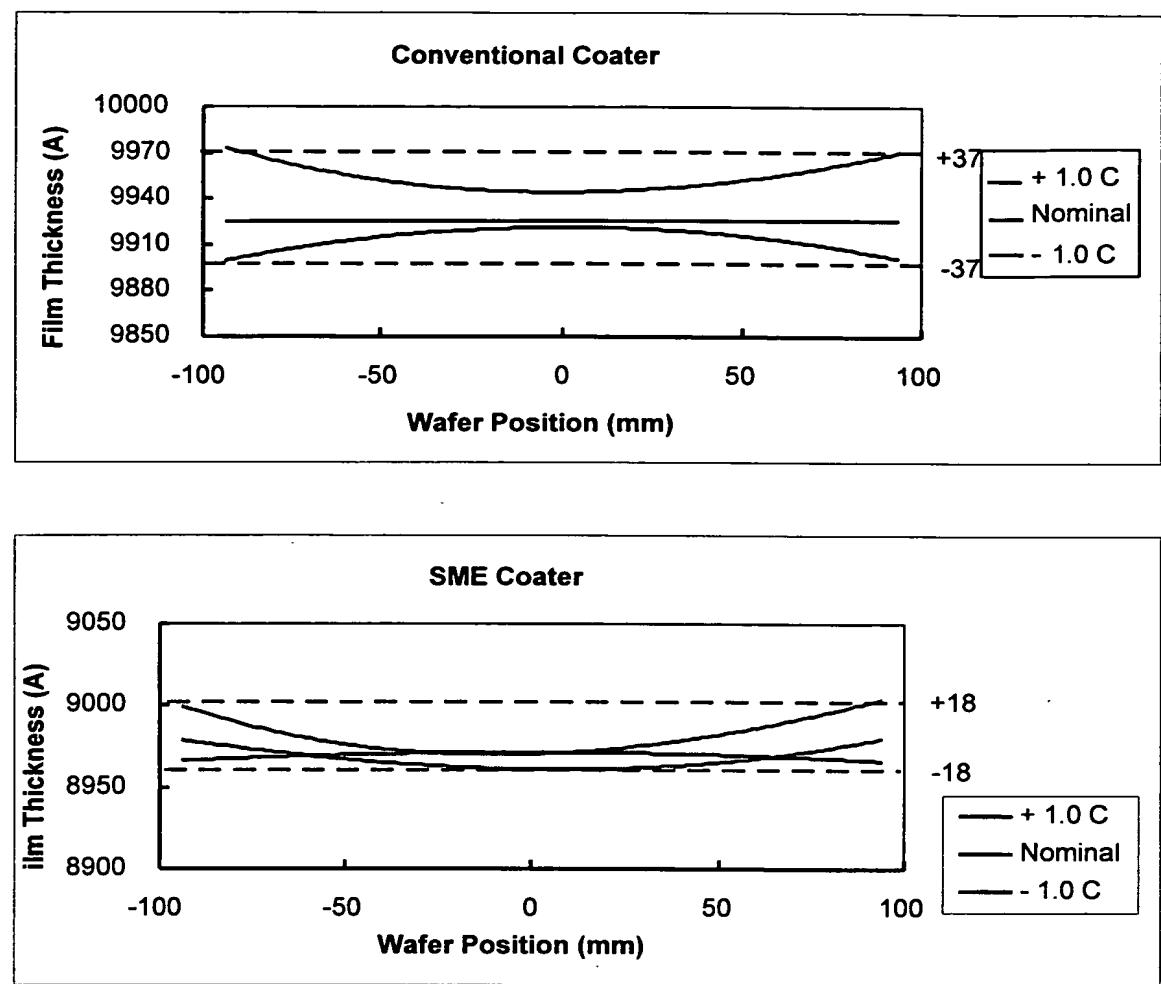
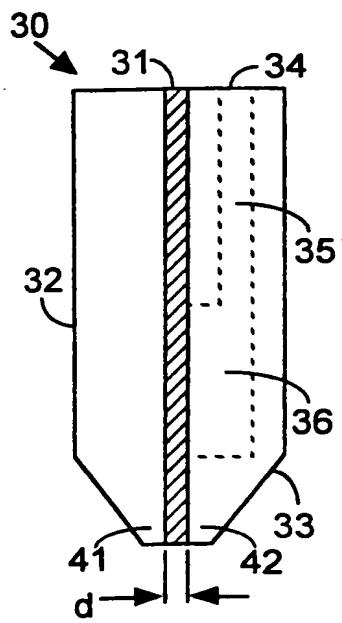
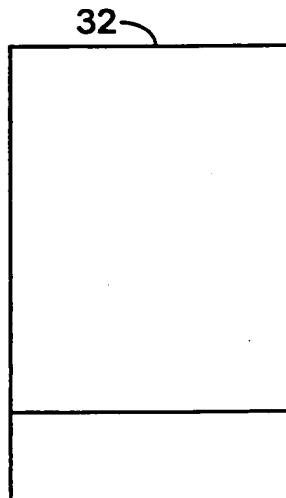


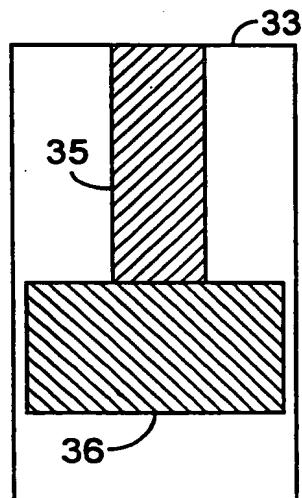
Figure 7: Chill plate temperature latitude comparison of the invention (SME) and conventional coaters for 200mm wafers. The SME coater chill plate temperature latitude of film uniformity is 43% wider than that of a conventional coater.



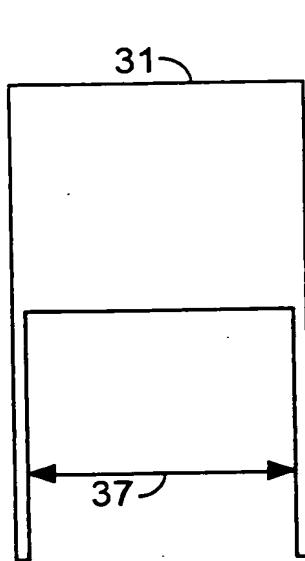
**FIG. 8**



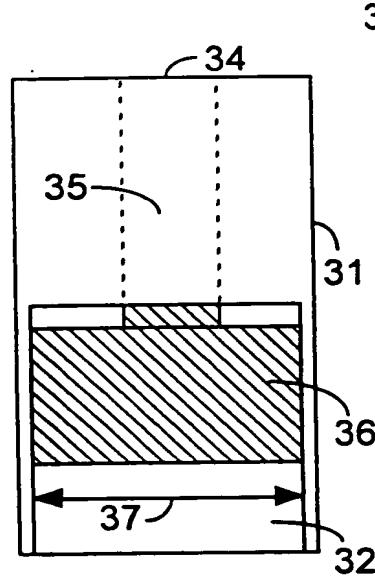
**FIG. 9**



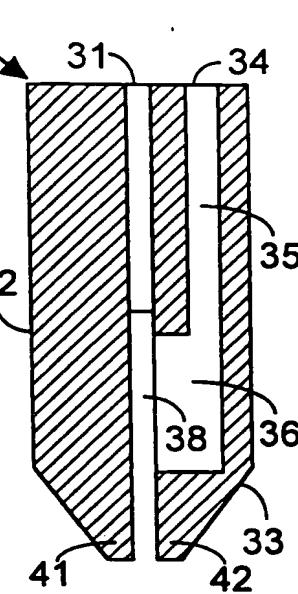
**FIG. 10**



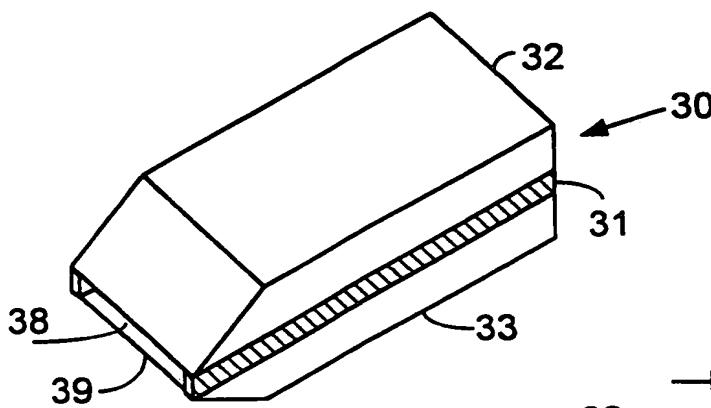
**FIG. II**



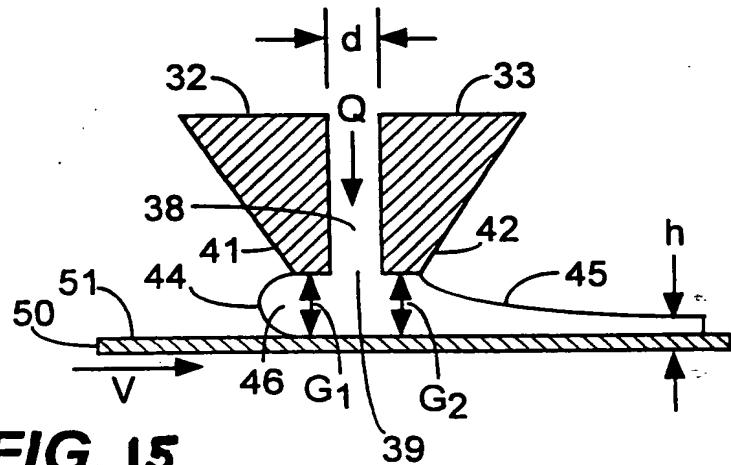
**FIG. 12**



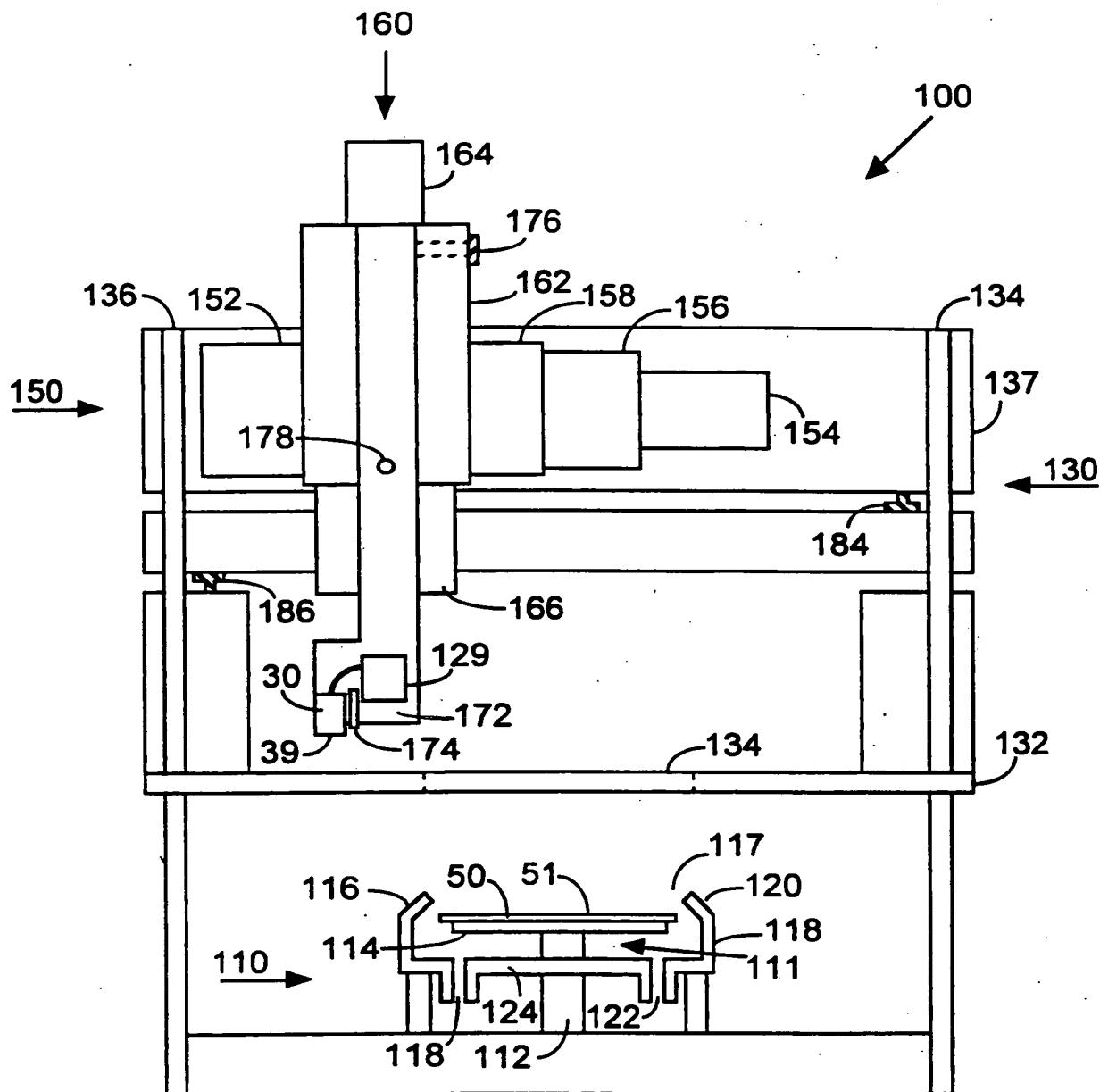
**FIG. 13**



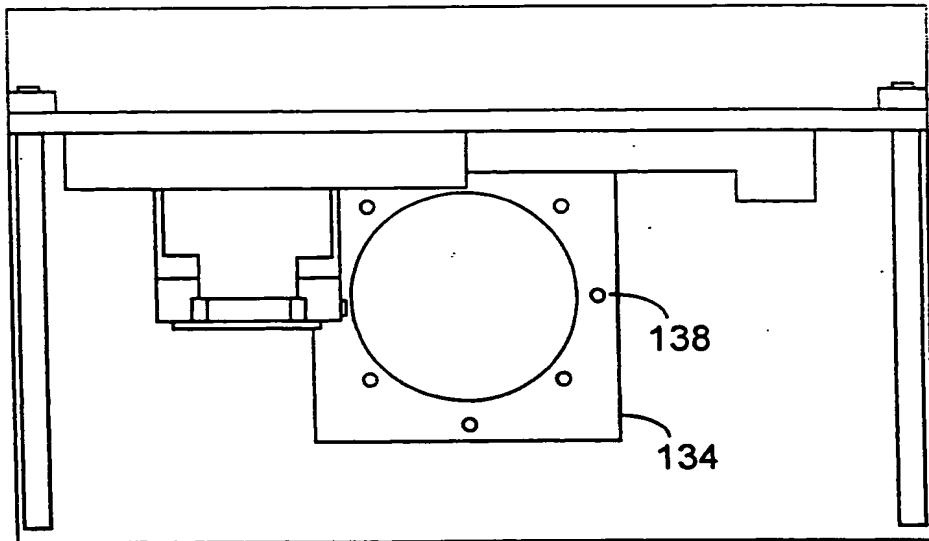
**FIG. 14**



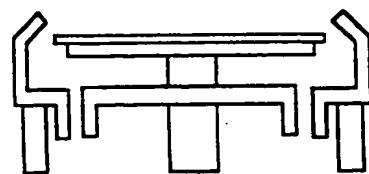
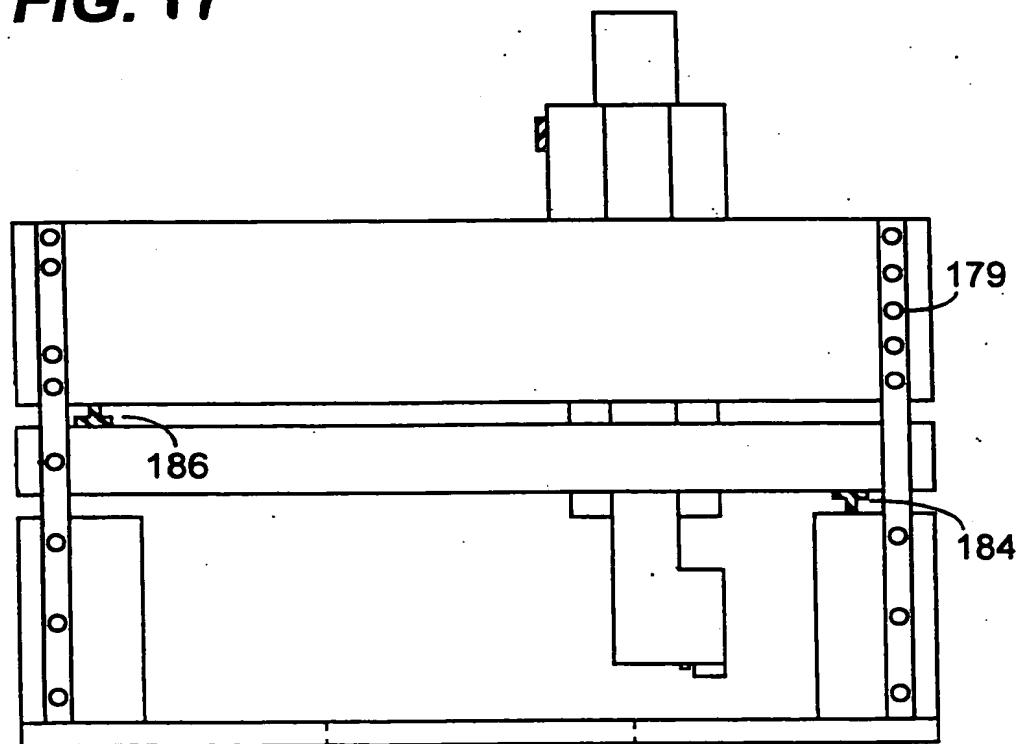
**FIG. 15**



**FIG. 16**

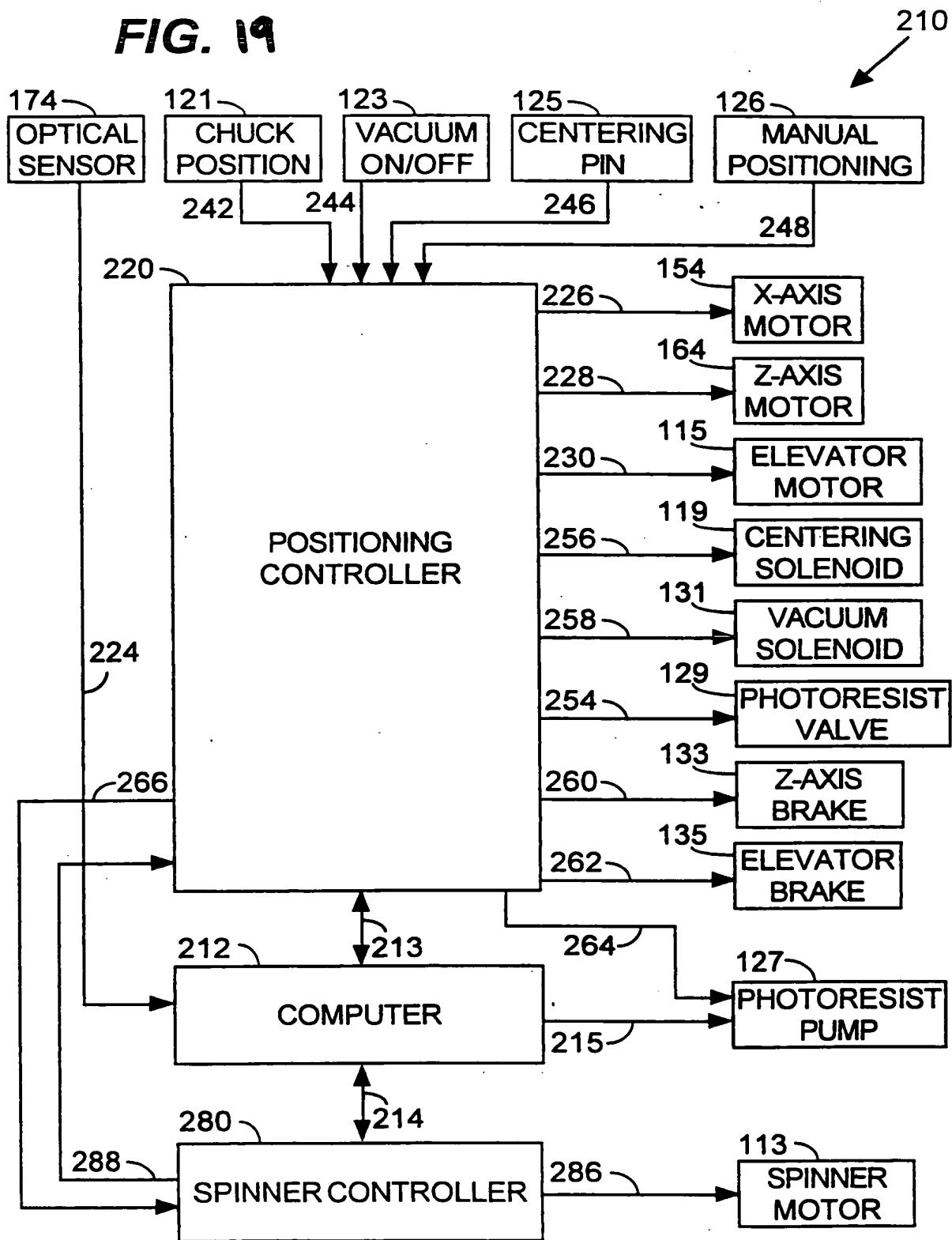


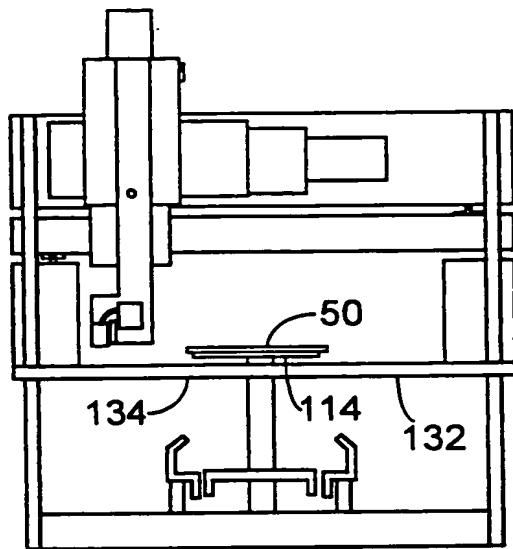
**FIG. 17**



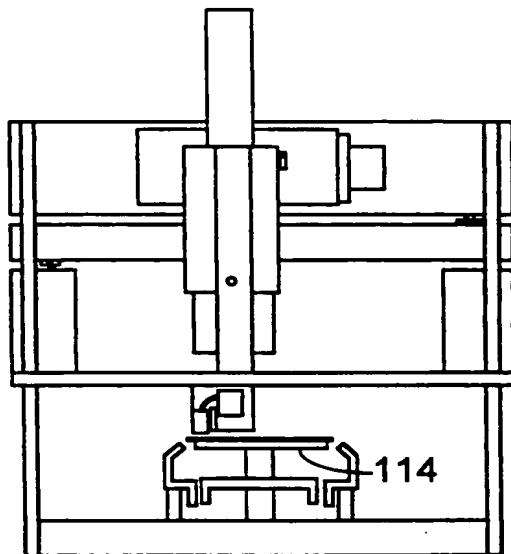
**FIG. 18**

**FIG. 19**

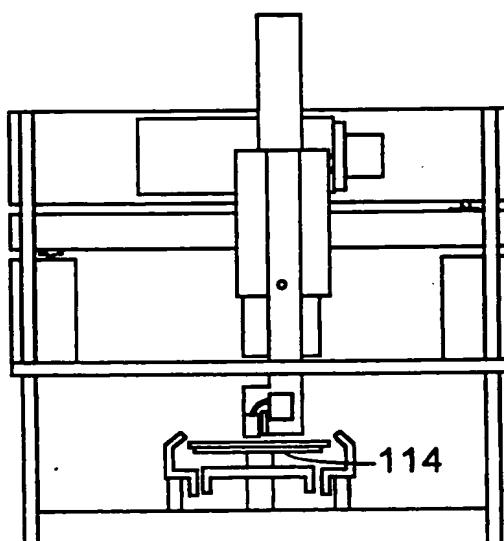




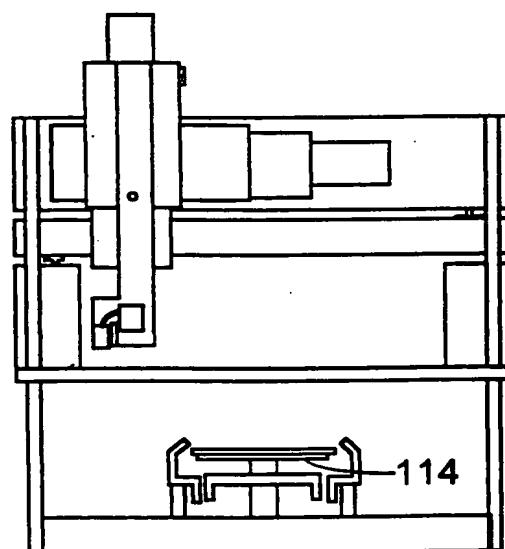
**FIG. 20**



**FIG. 21**

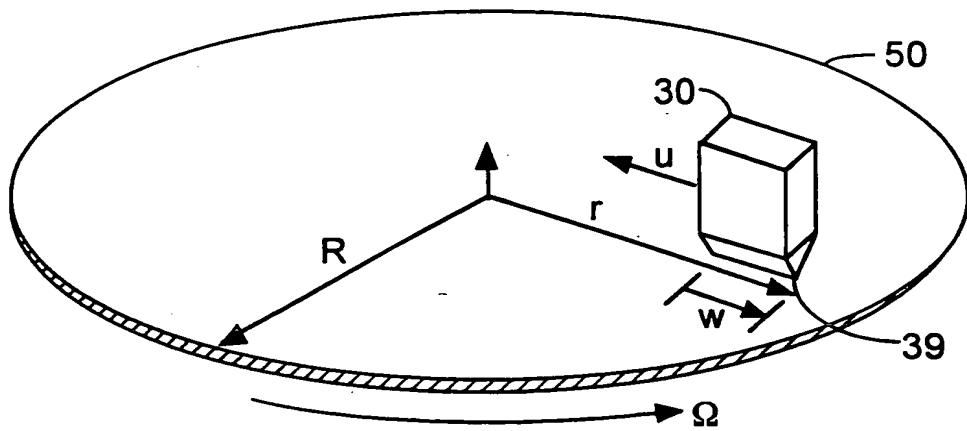


**FIG. 22**

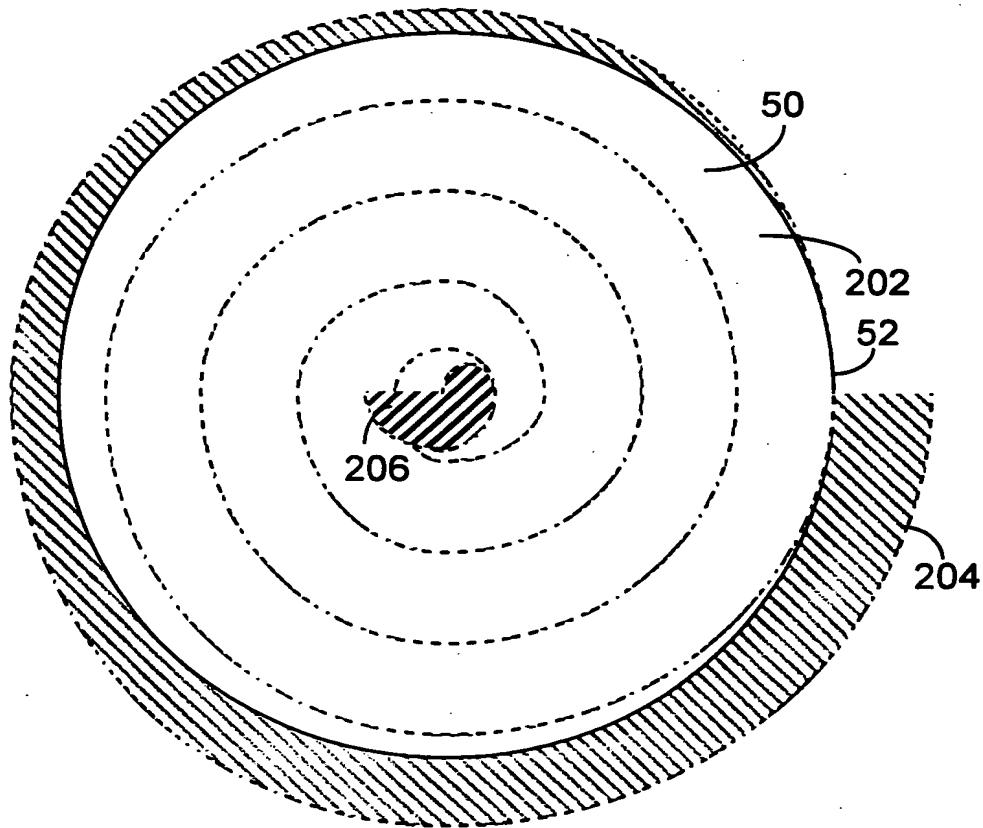


**FIG. 23**

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**FIG. 24**



**FIG. 25**